MOSFET – Power, N-Channel, SO-8 30 V, 17 A

Features

- Low R_{DS(on)} to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- DC-DC Converters
- Points of Loads
- Power Load Switch
- Motor Controls

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

| Param | Symbol | Value | Unit | | |
|---|---------------------------------------|---------------------------|----------------|------|---|
| Drain-to-Source Voltage | V_{DSS} | 30 | V | | |
| Gate-to-Source Voltage | | | V_{GS} | ±20 | V |
| Continuous Drain | Steady | T _A = 25°C | I _D | 14.1 | Α |
| Current R _{θJA} (Note 1) | State | T _A = 70°C | | 11.3 | |
| Power Dissipation $R_{\theta JA}$ (Note 1) | Steady T _A = 25°C State | | P _D | 1.46 | W |
| Continuous Drain | Steady | T _A = 25°C | I _D | 10.6 | Α |
| Current R _{θJA} (Note 2) | State | T _A = 70°C | | 8.5 | |
| Power Dissipation $R_{\theta JA}$ (Note 2) | | T _A = 25°C | P _D | 0.82 | W |
| Continuous Drain | Steady | T _A = 25°C | I _D | 17 | Α |
| Current $R_{\theta JA}$, $t \le 10 s$ (Note 1) | State | T _A = 70°C | | 13.6 | |
| Power Dissipation $R_{\theta JA}$, $t \le 10 \text{ s(Note 1)}$ | Steady State | | | 2.12 | W |
| Pulsed Drain Current | $T_A = 25^{\circ}$ | C, t _p = 10 μs | I_{DM} | 136 | Α |
| Operating Junction and S | T _J , T _{stg} | –55 to 150 | ç | | |
| Source Current (Body Did | I _S | 2.1 | Α | | |
| Single Pulse Drain-to-So $(T_J=25^{\circ}C,V_{DD}=30V,V_{L}=18A_{pk},L=1.0$ mH, F | E _{AS} | 162 | mJ | | |
| Lead Temperature for So (1/8" from case for 10 s) | TL | 260 | °C | | |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

| Parameter | Symbol | Value | Unit |
|---|-----------------|-------|------|
| Junction-to-Ambient - Steady State (Note 1) | $R_{\theta JA}$ | 85.5 | °C/W |
| Junction-to-Ambient – $t \le 10 \text{ s (Note 1)}$ | $R_{\theta JA}$ | 59 | |
| Junction-to-Foot (Drain) | $R_{\theta JF}$ | 25 | |
| Junction-to-Ambient - Steady State (Note 2) | $R_{\theta JA}$ | 152 | |

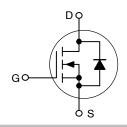


ON Semiconductor®

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| V _{(BR)DSS} | R _{DS(ON)} MAX | I _D MAX |
|----------------------|-------------------------|--------------------|
| 30 V | 4.3 mΩ @ 10 V | 17 A |
| | 5.7 mΩ @ 4.5 V | 17.8 |

N-Channel



PIN A 1 Source = SO-8 Source =

CASE 751

STYLE 12

MARKING DIAGRAM/ PIN ASSIGNMENT

Source Drain Source Drain Source Drain Source Drain Drain Top View

4920N = Device Code A = Assembly Location Y = Year

WW = Work Week
■ Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|-------------------|-----------------------|
| NTMS4920NR2G | SO-8 (Pb-Free) | 2500/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

| 1. 2. | Surfacemounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces). Surfacemounted on FR4 board using the minimum recommended pad size. |
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ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

| Parameter | Symbol | Test Condition | on | Min | Тур | Max | Unit |
|--|--------------------------------------|--|------------------------|-----|------|------|-------------|
| OFF CHARACTERISTICS | | | | | | | |
| Drain-to-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$ | | 30 | | | V |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | V _{(BR)DSS} /T _J | | | | 12.2 | | mV/°C |
| Zero Gate Voltage Drain Current | I _{DSS} | | T _J = 25°C | | | 1.0 | μΑ |
| | | $V_{GS} = 0 \text{ V}, V_{DS} = 24 \text{ V}$ | T _J = 125°C | | | 10 | 1 |
| Gate-to-Source Leakage Current | I _{GSS} | V _{DS} = 0 V, V _{GS} = | ±20 V | | | ±100 | nA |
| ON CHARACTERISTICS (Note 3) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | $V_{GS} = V_{DS}, I_D = 2$ | 250 μΑ | 1.0 | | 2.5 | V |
| Negative Threshold Temperature Coefficient | V _{GS(TH)} /T _J | | | | 5.4 | | mV/°C |
| Drain-to-Source On Resistance | R _{DS(on)} | $V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 6.5 \text{ A}$ | | | 3.6 | 4.3 | mΩ |
| | | | | | 4.6 | 5.7 | 1 |
| Forward Transconductance | 9FS | V _{DS} = 1.5 V, I _D = | 7.5 A | | 30.8 | | S |
| CHARGES, CAPACITANCES AND GA | ATE RESISTAN | NCE | | | | 1 | |
| Input Capacitance | C _{iss} | V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 25 V | | | 4068 | | pF |
| Output Capacitance | C _{oss} | | | | 1170 | | 1 |
| Reverse Transfer Capacitance | C _{rss} | | | | 41 | | 1 |
| Total Gate Charge | Q _{G(TOT)} | V _{GS} = 4.5 V, V _{DS} = 15 V, I _D = 7.5 A | | | 26.3 | | nC |
| Threshold Gate Charge | Q _{G(TH)} | | | | 6.4 | | - - - |
| Gate-to-Source Charge | Q _{GS} | | | | 10.4 | | |
| Gate-to-Drain Charge | Q_{GD} | | | | 3.8 | | |
| Total Gate Charge | Q _{G(TOT)} | V _{GS} = 10 V, V _{DS} = 15 V, I _D = 7.5 A | | | 58.9 | | nC |
| SWITCHING CHARACTERISTICS (No | ote 4) | | • | | | • | • |
| Turn-On Delay Time | t _{d(on)} | | | | 15.3 | | ns |
| Rise Time | t _r | V _{GS} = 10 V. V _{DS} = | = 15 V. | | 4.7 | | 1 |
| Turn-Off Delay Time | t _{d(off)} | V _{GS} = 10 V, V _{DS} = I _D = 1.0 A, R _G = | 6.0 Ω | | 68.6 | | 1 |
| Fall Time | t _f | 1 | ļ | | 42.2 | | 1 |
| DRAIN-SOURCE DIODE CHARACTE | RISTICS | | • | | | • | • |
| Forward Diode Voltage | V_{SD} | | T _J = 25°C | | 0.7 | 1.0 | V |
| | | $V_{GS} = 0 \text{ V}, I_{S} = 2.0 \text{ A}$ | T _J = 125°C | | 0.53 | | 1 |
| Reverse Recovery Time | t _{RR} | | | | 50.3 | | ns |
| Charge Time | ta | $V_{GS} = 0 \text{ V, } d_{IS}/d_t = 100 \text{ A/}\mu\text{s,}$ $I_S = 2.0 \text{ A}$ | | | 25.7 | | 1 |
| Discharge Time | t _b | | | | 24.6 | | 1 |
| Reverse Recovery Charge | Q _{RR} | | | | 65 | | nC |
| PACKAGE PARASITIC VALUES | - | | | | - | - | <u>-</u> |
| Source Inductance | L _S | | | | 0.66 | | nH |
| Drain Inductance | L _D | . | | | 0.2 | | 1 |
| Gate Inductance | L _G | T _A = 25°C | | | 1.5 | | 1 |
| Gate Resistance | R _G | 1 | ŀ | | 0.4 | 1.0 | Ω |
| | ı. | ı | | | | | • |

Pulse Test: pulse width = 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

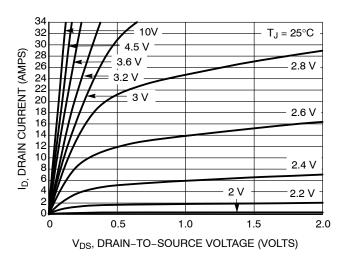
TYPICAL PERFORMANCE CURVES

65

60

55

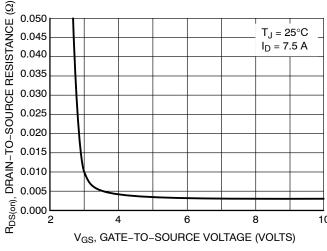
 $V_{DS} \ge 10 \text{ V}$



ID, DRAIN CURRENT (AMPS) 50 45 40 35 30 25 20 $T_J = 125^{\circ}C$ 15 $T_J = 25^{\circ}C$ 10 $T_J = -55^{\circ}C$ 0 1.5 2.5 3 3.5 4.5

Figure 1. On-Region Characteristics

V_{GS}, GATE-TO-SOURCE VOLTAGE (VOLTS) Figure 2. Transfer Characteristics



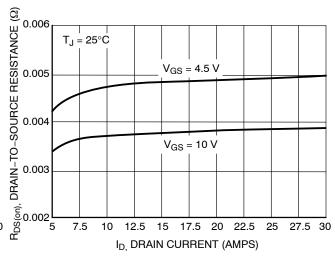
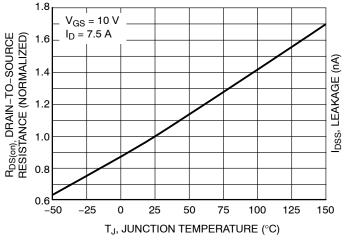


Figure 3. On-Resistance vs. Gate-to-Source Voltage

Figure 4. On-Resistance vs. Drain Current and **Gate Voltage**



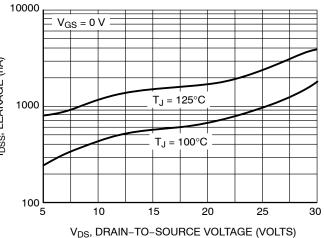


Figure 5. On-Resistance Variation with **Temperature**

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES

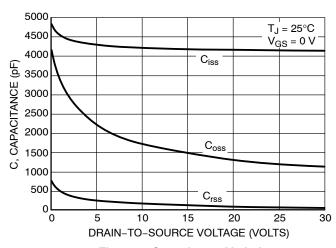


Figure 7. Capacitance Variation

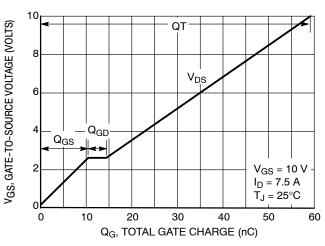


Figure 8. Gate-To-Source and Drain-To-Source Voltage vs. Total Charge

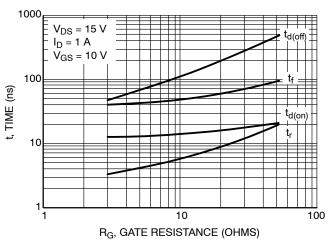


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

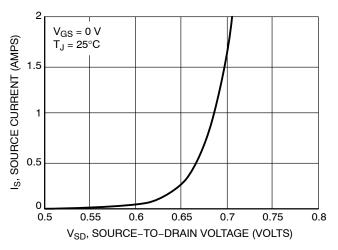


Figure 10. Diode Forward Voltage vs. Current

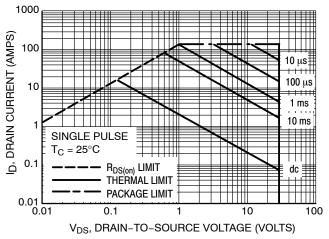


Figure 11. Maximum Rated Forward Biased Safe Operating Area

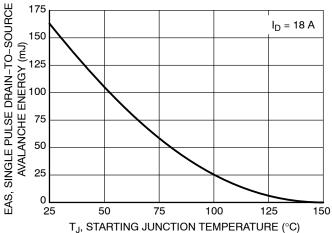


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature



SOIC-8 NB CASE 751-07 **ISSUE AK**

DATE 16 FEB 2011



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

| | MILLIMETERS | | INCHES | | |
|-----|-------------|----------|-------------|-------|-------|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 4.80 | 5.00 | 0.189 | 0.197 | |
| В | 3.80 4.00 | | 0.150 | 0.157 | |
| С | 1.35 1.75 | | 0.053 | 0.069 | |
| D | 0.33 0.51 | | 0.013 | 0.020 | |
| G | 1.27 | 1.27 BSC | | 0 BSC | |
| Н | 0.10 0.25 | | 0.004 | 0.010 | |
| J | 0.19 0.25 | | J 0.19 0.25 | 0.007 | 0.010 |
| K | 0.40 1.27 | | 0.016 | 0.050 | |
| М | 0 ° | 0 ° 8 ° | | 8 ° | |
| N | 0.25 | 0.50 | 0.010 | 0.020 | |
| S | 5.80 6.20 | | 0.228 | 0.244 | |

SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

= Wafer Lot = Year = Work Week

= Pb-Free Package



XXXXXX = Specific Device Code = Assembly Location Α

= Year ww = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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SOIC-8 NB CASE 751-07 ISSUE AK

DATE 16 FEB 2011

| STYLE 3: PIN 1. DRAIN, PIE #1 CTOR, #1 CTOR, #2 CTOR, #1 CTOR, #2 CTOR, #2 CTOR, #2 CTOR, #2 CTOR, #1 | 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #1 Vd STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN 8. TYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #1 |
|---|---|
| E PIN 1. INPUT 2. EXTERNAL BY 3. THIRD STAGE 4. GROUND E 5. DRAIN 6. GATE 3 7. SECOND STAGE 8. FIRST STAGE STYLE 11: ID PIN 1. SOURCE 1 2. GATE 1 T 3. SOURCE 2 ID 4. GATE 2 ID 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 ID 8. DRAIN 1 ID | PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 Vd 8. COLLECTOR, #1 STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN 8. TYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 |
| ID PIN 1. SOURCE 1 2. GATE 1 T 3. SOURCE 2 ID 4. GATE 2 ID 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 ID 8. DRAIN 1 STYLE 15: RCE PIN 1. ANODE 1 E 2. ANODE 1 RCE 3. ANODE 1 | PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 |
| STYLE 15: RCE PIN 1. ANODE 1 E 2. ANODE 1 RCE 3. ANODE 1 | PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 |
| N 7. CATHODE, CON N 8. CATHODE, CON | MMON 5. COLLECTOR, DIE #2 MMON 6. COLLECTOR, DIE #2 MMON 7. COLLECTOR, DIE #1 MMON 8. COLLECTOR, DIE #1 |
| STYLE 19: PIN 1. SOURCE 1 E 2. GATE 1 E 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 DE 7. DRAIN 1 DE 8. MIRROR 1 | STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN |
| STYLE 23: E1 PIN 1. LINE 1 IN DN CATHODE/VCC 2. COMMON ANC DN CATHODE/VCC 3. COMMON ANC E3 4. LINE 2 IN DN ANODE/GND 5. LINE 2 OUT E4 6. COMMON ANC E5 7. COMMON ANC DN ANODE/GND 8. LINE 1 OUT | ODE/GND 2. EMITTER ODE/GND 3. COLLECTOR/ANODE |
| STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN | STYLE 28: PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V MON 6. VBULK 7. VBULK 8. VIN |
| 1 1 | |
| ; | STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ E 5. SOURCE E 6. SOURCE E 7. SOURCE 8. DRAIN |

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